

## **TP0v recap and objectives**

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# Focus Group Participants & Contributors

Following a Jan 2020 presentation ([mellitz 3ck 01a 0120](#)) showing high ambiguity in TPOa implementation and the following idea of having a varying TX TP instead, a brainstorming group was formed.

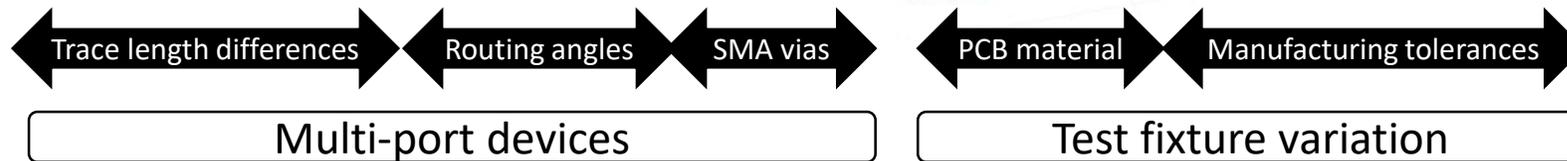
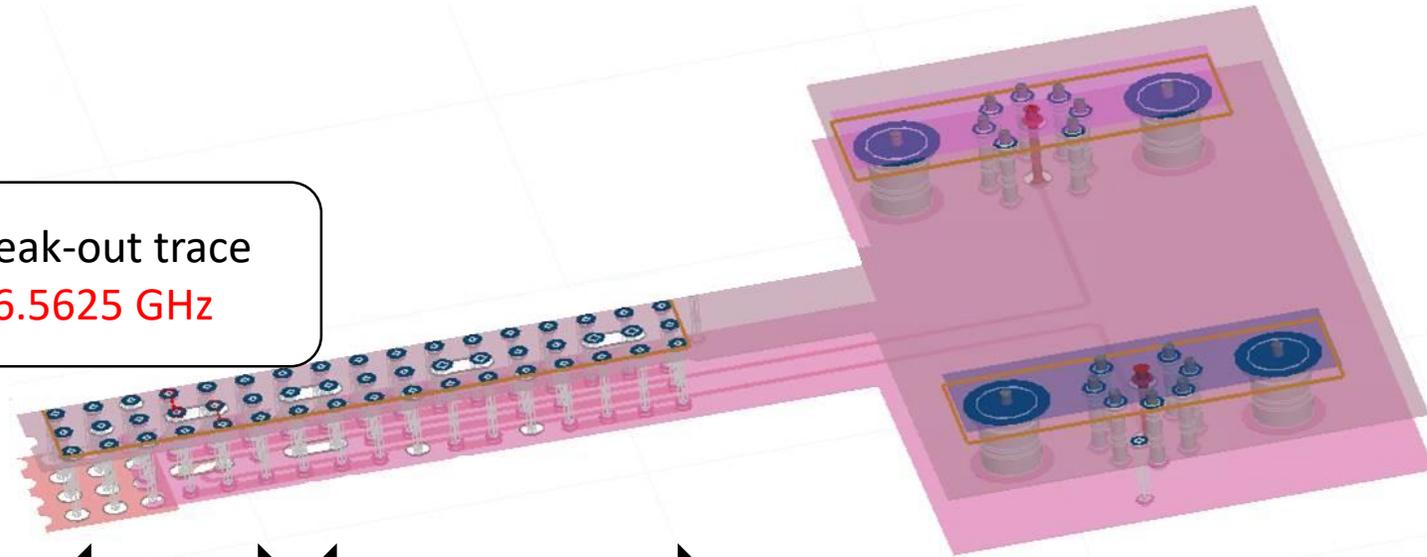
Thoughts, feedback and recommendations of a group of contributors in multiple teleconference sessions were combined to a recommendation (summarized in BenArtsi\_3ck\_01\_0720) and adopted to the baseline

Workgroup consisted of:

- ❑ Matt Brown, Huawei Technologies Canada
- ❑ Piers Dawe, Mellanox
- ❑ Howard Heck, Intel
- ❑ Phil Sun, Credo
- ❑ Rich Mellitz, Samtec
- ❑ Adee Ran, Intel
- ❑ Liav Ben-Artsi, Marvell Semiconductor

# Rcap: Why Throw Away the “Good-Old method” of specs at TP0a?

Even with high quality material, ~2.4mm via → break-out trace from an internal ball →  $\mu\text{via}$  to SMA  $\geq 3\text{dB}$  @ 26.5625 GHz



- ❑ These inaccuracies makes TP0-TP0a **highly implementation and manufacturing dependent** → **Ambiguity!** Implementation and results will vary
- ❑ “Can’t you de-embed the fixture?!”
- ❑ Just thinking:

It is easier to *measure* a test fixture than to *de-embed* it!

# Should we be concerned about the new method?

- ❑ The focus group identified multiple parameters which pass bar should not vary with TP location (in back-up slides)
- ❑ And the things that change?! A methodology was suggested regarding these (in back-up slides)
  - The idea to allow the TP location and loss to vary is new
  - The manner by which one can achieve the pass criteria per TP0-TP0v implementation is actually not that new...

# Looking forward

- ✓ Ambiguity was avoided by shifting from TP0a to TP0v
- ✓ Multi-lane measurement was made possible
- ❑ There are a few TBDs yet to be defined regarding TP0v
- ❑ Informative TP TBDs to be defined
- ❑ Close the gaps in the “new” methodology
- ❑ In particular cases can re-form a brainstorming group to achieve consensus on closing gaps and TBDs

**THANK YOU**

## **Backup Slides**

# Measurements which do not vary with TP location

## Thus, no need to change specs

- ❑ Signaling rate
- ❑ Differential pk-pk voltage (max) Tx disabled/enabled
- ❑ DC common mode voltage (max/min)
- ❑ AC common mode voltage RMS (fixture has low effect)
- ❑ Transmitter steady state voltage (max/min)
- ❑ Transmitter waveform
  - The method for finding Tx FFE taps is independent of TP0-TP0a; actually works even at TP2.
  - See: [http://www.ieee802.org/3/cb/public/jan16/mellitz\\_cb\\_01a\\_0116.pdf](http://www.ieee802.org/3/cb/public/jan16/mellitz_cb_01a_0116.pdf) slide 6-15  
C is vector of tap coefficients. P is fitted un-equalized pulse response. R is the fitted equalized pulse response.  $C = (R^T R)^{-1} R^T P$ .
  - Need to make sure scope CDR can lock → suggested TP0-TP0v loss ≤ 5dB @ 26.5625GHz;  $ILD \leq Loss/20$   
(2dB ≤ Loss ≤ 5dB → 0.25dB for 5dB loss)
- ❑ SNDR – Tx parameters to be measured on an optimized test board, breakout section is part of the device budget; package/breakout Xtalk is included in measurement

# Parameters that should be measured with adjustment to overcome test fixture loss

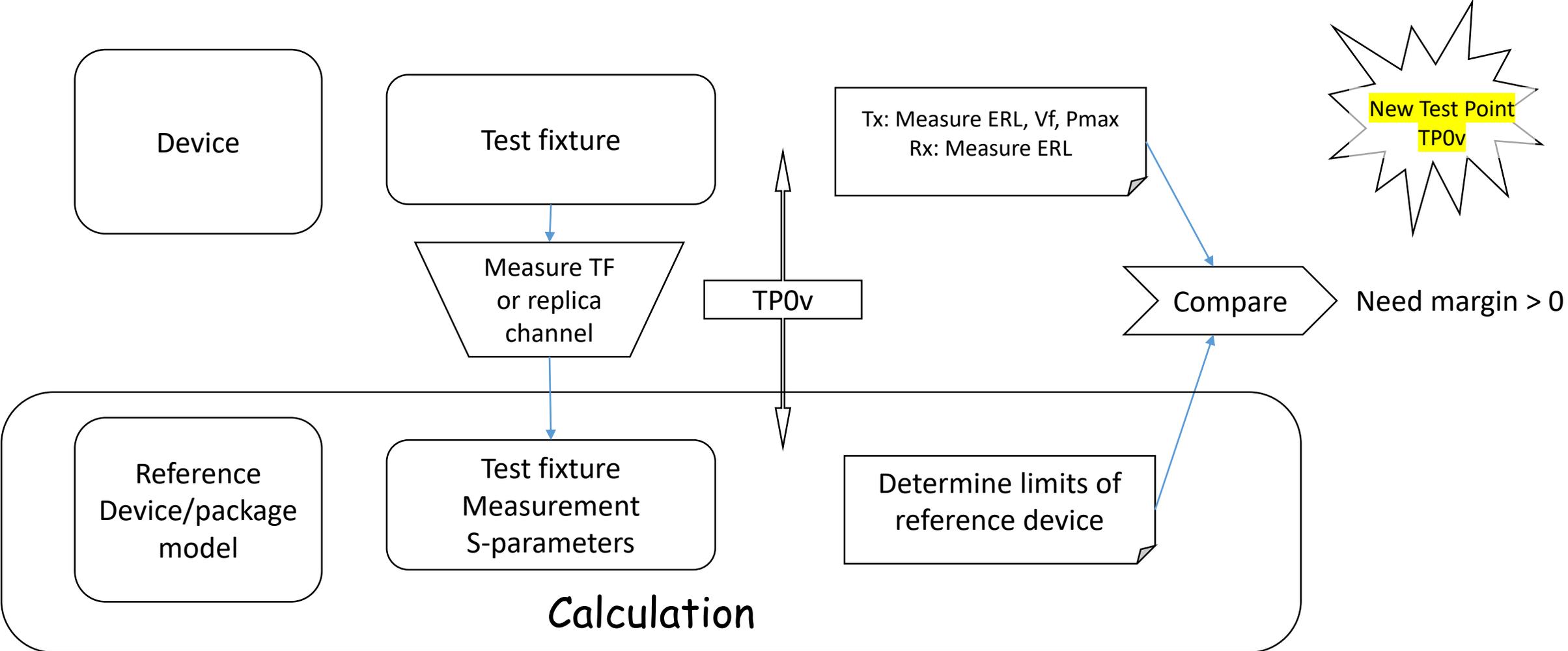
## □ Jitter

- In D1.2: “jitter measurements are made with a single transmit equalizer setting selected to compensate for the loss of the transmitter package and TPO to TPOa test fixture”
- Need to be clarified to avoid ambiguity
- Spec limit value can stay unchanged

## □ RLM

- In Annex 120D it is under **Output waveform** for which “The state of the transmit equalizer is controlled by management interface “
- Clarify that Tx equalization should be used to get clean level measurements
- Spec limit value can stay unchanged

# Enabling implementation-dependent test fixture



# Proposed new Methodology

- ❑ Measure TP0-TP0v channel (or replica) for the device/lane under test
- ❑ Concatenate Tr filter, Tx reference device and package model, and B-T measurement filter (same equations used in COM)
- ❑ Using the concatenated channel, calculate an output pulse response (with minimum  $A_v$ ) and TDR at TP0v, with ideal termination
- ❑ Calculate  $V_f$ ,  $V_{peak}/V_f$ , and ERL
  - The results are the expected parameters of the reference Tx at this TP0v
  - This is the bar that the DUT should be compared to!
- ❑ Now measure  $V_f$ ,  $V_{peak}$ , and ERL of the DUT at TP0v using existing method
- ❑ Margin from the calculated reference values → pass/fail